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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/743,135	12/23/2003	Shih-Fan Kuan	4392-0149P	7481
	7590 03/22/200 ART KOLASCH & BI	EXAMINER		
PO BOX 747	XXX XXX 00040 0040	CHACKO DAVIS, DABORAH		
FALLS CHURCH, VA 22040-0747			ART UNIT	PAPER NUMBER
			1756	
SHORTENED STATUTORY	PERIOD OF RESPONSE	NOTIFICATION DATE	DELIVERY MODE	
3 MONTHS		03/22/2007	ELECTRONIC	

Please find below and/or attached an Office communication concerning this application or proceeding.

If NO period for reply is specified above, the maximum statutory period will apply and will expire 6 MONTHS from the mailing date of this communication.

Notice of this Office communication was sent electronically on the above-indicated "Notification Date" and has a shortened statutory period for reply of 3 MONTHS from 03/22/2007.

Notice of the Office communication was sent electronically on above-indicated "Notification Date" to the following e-mail address(es):

mailroom@bskb.com

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	10/743,135	KUAN ET AL.
Office Action Summary	Examiner	Art Unit
	Daborah Chacko-Davis	1756
	nication appears on the cover sheet with	n the correspondence address
Period for Reply A SHORTENED STATUTORY PERIOD & WHICHEVER IS LONGER, FROM THE & - Extensions of time may be available under the provision after SIX (6) MONTHS from the mailing date of this com - If NO period for reply is specified above, the maximum is Failure to reply within the set or extended period for reply Any reply received by the Office later than three months	MAILING DATE OF THIS COMMUNIC, is of 37 CFR 1.136(a). In no event, however, may a repumunication. Statutory period will apply and will expire SIX (6) MONTI by will, by statute, cause the application to become ABA	ATION. oly be timely filed HS from the mailing date of this communication. NDONED (35 U.S.C. § 133).
earned patent term adjustment. See 37 CFR 1.704(b).		
Status 		·
1) Responsive to communication(s) fil		
2a)⊠ This action is FINAL.	2b) This action is non-final.	•
	for allowance except for formal matter	
closed in accordance with the pract	tice under Ex parte Quayle, 1935 C.D.	11, 453 O.G. 213.
Disposition of Claims		
4) ☐ Claim(s) 1-15 is/are pending in the 4a) Of the above claim(s) is/a 5) ☐ Claim(s) is/are allowed. 6) ☐ Claim(s) 1-15 is/are rejected. 7) ☐ Claim(s) is/are objected to. 8) ☐ Claim(s) are subject to restrict to the subject to restrict the subject the subject to restrict the subject the subjec	are withdrawn from consideration.	
Application Papers		
9)☐ The specification is objected to by the	ne Examiner.	
10)☐ The drawing(s) filed on is/are	e: a)□ accepted or b)□ objected to by	y the Examiner.
	ection to the drawing(s) be held in abeyance	` '
<u> </u>	g the correction is required if the drawing(s	, ,
11)☐ The oath or declaration is objected t	to by the Examiner. Note the attached	Office Action or form PTO-152.
Priority under 35 U.S.C. § 119		
3. Copies of the certified copies application from the Internation		plication No eceived in this National Stage
. •		
Attachment(s)		
Notice of References Cited (PTO-892) Notice of Draftsperson's Patent Drawing Review (IB) Information Disclosure Statement(s) (PTO/SB/08) Paper No(s)/Mail Date	PTO-948) Paper No(s)/	mmary (PTO-413) Mail Date ormal Patent Application -

DETAILED ACTION

Claim Rejections - 35 USC § 103

- 1. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:
 - (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.
- 2. Claims 1-15, are rejected under 35 U.S.C. 103(a) as being unpatentable over U.
- S. Patent No. 6,436,762 (Tzeng et al., hereinafter referred to as Tzeng) in view of U. S. Patent Application Publication No. 2001/0046761 (Chung et al., hereinafter referred to as Chung).

Tzeng, in col 3, lines 38-46, in col 4, lines 1-67, discloses a method of forming bit-line contact for DRAM devices by forming gate electrodes (control gates) on the substrate, forming a BPSG dielectric layer on the gate electrodes, performing a first planarization using a CMP process (chemical mechanical polishing), and forming a photoresist pattern on the BPSG dielectric layer followed by etching through the opening in the mask (self-aligned etching) to form a bit-contact opening (bit-line contact window), depositing a conductive layer so as to concurrently fill in the bit-line opening to form a bit-line contact, performing a CMP planarization (polished back) on the conductive layer till the conductive plugs (bit-line contact) are formed (removing all the conductive layer and mask layers till the dielectric layer is revealed), forming a TEOS layer (isolation layer) on the dielectric layer and the plug, forming an opening (aperture) in the TEOS layer such that the opening is aligned with the bit-line contact, followed by

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selective etching of a portion of the exposed bit-line contact, conformally forming a conductive plug in the opening (filling the opening with conductive material) (claims 1-4, 7, 9-14). Tzeng, in col 4, lines 1-12, discloses the use of silicon nitride as the mask (patterned photoresist) (claim 5). Tzeng, in col 4, lines 28-30, and in col 5, lines 15-17, discloses forming a photoresist mask by etching (claim 6). Tzeng, in col 4, lines 28-37, and in col 5, lines 60-67, discloses that the conductive layer (conductive plug) is a polysilicon material or a tungsten plug (metallic material) (claims 8and 15).

The difference between the claims and Tzeng is that Tzeng does not disclose planarizing the dielectric layer to expose the plurality of control gates.

Chung, in [0034], discloses planarizing the dielectric layer (insulating layer) till the gates (top surface of the gate electrodes') are exposed.

Therefore, it would be obvious to a skilled artisan to modify Tzeng by applying the CMP planarizing process on the dielectric layer till the gate electrodes are revealed as suggested by Chung, because Chung, in [0034], discloses that performing CMP on the insulating layer to reveal the gates enables the formation of a contact pad.

Response to Arguments

- 3. Applicant's arguments with respect to claims 1-15, have been considered but are most in view of the new ground(s) of rejection. Applicant's arguments filed December 28, 2006, have been fully considered but they are not persuasive.
- A) Applicants argue that Tzeng does not disclose planarizing the dielectric layer to expose the plurality of control gates.

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Tzeng is not depended upon to disclose planarizing the dielectric layer to expose the gates. Chung is depended upon to disclose exposing the top surfaces of the gates via dielectric layer planarization.

B) Applicants argue that Tzeng does not teach the issue between bit-line contact and the control gate.

In response to applicant's argument that the references fail to show certain features of applicant's invention, it is noted that the features upon which applicant relies (i.e., an issue between the bit-line contact and the control gate) are not recited in the rejected claim(s). Although the claims are interpreted in light of the specification, limitations from the specification are not read into the claims. See *In re Van Geuns*, 988 F.2d 1181, 26 USPQ2d 1057 (Fed. Cir. 1993).

Conclusion

4. Applicant's amendment necessitated the new ground(s) of rejection presented in this Office action. Accordingly, **THIS ACTION IS MADE FINAL**. See MPEP § 706.07(a). Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a).

A shortened statutory period for reply to this final action is set to expire THREE MONTHS from the mailing date of this action. In the event a first reply is filed within TWO MONTHS of the mailing date of this final action and the advisory action is not mailed until after the end of the THREE-MONTH shortened statutory period, then the shortened statutory period will expire on the date the advisory action is mailed, and any extension fee pursuant to 37 CFR 1.136(a) will be calculated from the mailing date of

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the advisory action. In no event, however, will the statutory period for reply expire later than SIX MONTHS from the date of this final action.

5. Any inquiry concerning this communication or earlier communications from the examiner should be directed to Daborah Chacko-Davis whose telephone number is (571) 272-1380. The examiner can normally be reached on M-F 9:30 - 6:00. If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Mark F Huff can be reached on (571) 272-1385. The fax phone number for the organization where this application or proceeding is assigned is (571) 273-8300. Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

March 14, 2007.

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